Product / Process Change Notification



N° 2017-005-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Capacity extension by introduction of 300mm wafer diameter for dedicated OptiMOS[™]5 25V and 60V products at Infineon Villach, Austria

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 19. May 2017.
- Infineon aligns with the widely-recognized JEDEC STANDARD"JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG Postal Address Headquarters: Am Campeon 1-12, D-85579 Neubiberg, Phone +49 (0)89 234-0 Chairman of the Supervisory Board: Wolfgang Mayrhuber Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck Registered Office: Neubiberg Commercial Register Amtsgericht München HRB 126492

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► **Products affected:** See affected product list (1_cip17005_a)

► Detailed Change Information:

Subject:	 Introduction of 300mm wafer diameter at Infineon Technologies Austria AG. Interlayer dielectric form for OptiMOS™5 25V products with 300mm Silicon. Standardization of mould compound for TDSON-8 package Standardization of bond pad metallization stack 			
Reason:	 Next phase of Front End capacity expansion by introduction of 300mm wafer diameter to support continuous increasing customer demand in the future. Continuous process improvements with latest technology trends on state of the art FE production equipment and tools. Infineon is standardizing: mould compound for all of its OptiMOS[™] 60V products in TDSON-8 package. bond pad metallization stack 			
Description:	Old	New		
Wafer diameter:	 Infineon Technologies Austria AG, Villach, Austria (200mm) 	 Infineon Technologies Austria AG, Villach, Austria (200mm and 300mm) 		
Lot number & Label:	VExxxxxx = 200mm production	• VExxxxx = 200mm production Infineon Image: Comparison of the comp		

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Standardizing mould Hitachi CEL 1772 compound TDSON-8 package: Hitachi CEL 9240

- Standardization of source & gate pad metallization stack allows Infineon to improve quality and efficiency in the manufacturing environment by reducing complexity during the whole production chain.
- The Interlayer dielectric form follows the process based on state of the art 300mm production equipment and tools for OptiMOS™5 25V products.

Product Identification:	Internal traceability assured via Baunumber, Lotnumber and date code	
	External traceability assured via Waferlot number printed on Barcode Product Label (refer to section "Lot number & Label" – page 2)	
Impact of Change:	NO change on electrical, thermal parameters and reliability as proven via product qualification and characterization.	
	NO change in existing datasheet parameters	
	NO change in quality and reliability. Processes are optimized to meet product performance according to already applied Infineon specification.	
Attachments:	1_cip17005_a Affected Product List	
Time Schedule:		
Final qualification report:	Available on request	
First samples available:	On request	

Intended start of delivery: 2017-06-01 or earlier pending on customer approval

If you have any questions, please do not hesitate to contact your local Sales office.

PCN N°

Capacity extension by introduction of 300mm wafer diameter for dedicated OptiMOS™ 5 25V and 60V products at Infineon Villach, Austria

Sales Name	SP number	OPN	Package
BSC009NE2LS5	SP001212764	BSC009NE2LS5ATMA1	PG-TDSON-8
BSC009NE2LS5I	SP001212434	BSC009NE2LS5IATMA1	PG-TDSON-8
BSC014N06NS	SP000924886	BSC014N06NSATMA1	PG-TDSON-8
BSC015NE2LS5I	SP001288138	BSC015NE2LS5IATMA1	PG-TDSON-8
BSC016N06NS	SP000924882	BSC016N06NSATMA1	PG-TDSON-8
BSC026NE2LS5	SP001212432	BSC026NE2LS5ATMA1	PG-TDSON-8
BSC028N06NS	SP000917416	BSC028N06NSATMA1	PG-TDSON-8
BSC028N06NS E8205	SP001370220	BSC028N06NSE8205ATMA1	PG-TDSON-8
BSC034N06NS	SP001067010	BSC034N06NSATMA1	PG-TDSON-8
BSC039N06NS	SP000985386	BSC039N06NSATMA1	PG-TDSON-8
BSC039N06NS E8205	SP001370218	BSC039N06NSE8205ATMA1	PG-TDSON-8
BSC0580NS	SP001624404	BSC0580NSATMA1	PG-TDSON-8
BSC066N06NS	SP001067000	BSC066N06NSATMA1	PG-TDSON-8
BSC097N06NS	SP001067004	BSC097N06NSATMA1	PG-TDSON-8
BSG0810NDI	SP001241674	BSG0810NDIATMA1	PG-TISON-8
BSG0811ND	SP001075902	BSG0811NDATMA1	PG-TISON-8
BSG0812ND	SP001164324	BSG0812NDATMA1	PG-TISON-8
BSG0813NDI	SP001241676	BSG0813NDIATMA1	PG-TISON-8
BSZ013NE2LS5I	SP001288148	BSZ013NE2LS5IATMA1	PG-TSDSON-8
BSZ014NE2LS5IF	SP001258924	BSZ014NE2LS5IFATMA1	PG-TSDSON-8
BSZ031NE2LS5	SP001385378	BSZ031NE2LS5ATMA1	PG-TSDSON-8
BSZ033NE2LS5	SP001288158	BSZ033NE2LS5ATMA1	PG-TSDSON-8
BSZ042N06NS	SP000917418	BSZ042N06NSATMA1	PG-TSDSON-8
BSZ068N06NS	SP001067002	BSZ068N06NSATMA1	PG-TSDSON-8
BSZ100N06NS	SP001067006	BSZ100N06NSATMA1	PG-TSDSON-8
IPA029N06N	SP001199858	IPA029N06NXKSA1	PG-TO220-3
IPA040N06N	SP001196264	IPA040N06NXKSA1	PG-TO220-3
IPA060N06N	SP001099646	IPA060N06NXKSA1	PG-TO220-3
IPB010N06N	SP000917410	IPB010N06NATMA1	PG-TO263-7
IPB014N06N	SP000917408	IPB014N06NATMA1	PG-TO263-7
IPB026N06N	SP000962142	IPB026N06NATMA1	PG-TO263-3
IPB057N06N	SP000962140	IPB057N06NATMA1	PG-TO263-3
IPD025N06N	SP000988276	IPD025N06NATMA1	PG-TO252-3
IPD053N06N	SP000962138	IPD053N06NATMA1	PG-TO252-3
IPI020N06N	SP000962132	IPI020N06NAKSA1	PG-TO262-3
IPI029N06N	SP000962134	IPI029N06NAKSA1	PG-TO262-3
IPP020N06N	SP000917406	IPP020N06NAKSA1	PG-TO220-3
IPP029N06N	SP000917404	IPP029N06NAKSA1	PG-TO220-3
IPP040N06N	SP000959820	IPP040N06NAKSA1	PG-TO220-3
IPP060N06N	SP000917402	IPP060N06NAKSA1	PG-TO220-3
IPT007N06N	SP001100158	IPT007N06NATMA1	PG-HSOF-8
TDA21231	SP001126808	TDA21231AUMA1	PG-IQFN-31
TDA21232	SP001164326	TDA21232AUMA1	PG-IQFN-31